### **MA21D38**

### Silicon epitaxial planar type

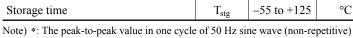
For high frequency rectification

#### ■ Features

- $I_{F(AV)} = 1$  A rectification is possible
- Low forward voltag V<sub>F</sub>
- High non-repetitive peak forward surge voltage

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit				
Reverse voltage	V <sub>R</sub>	30	V				
Maximum peak reverse voltage	$V_{RM}$	30	V				
Forward current (Average)	I <sub>F(AV)</sub>	1.0	A				
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	20	A				
Junction temperature	T <sub>j</sub>	125	°C				
Storage time	T <sub>stg</sub>	-55 to +125	°C				



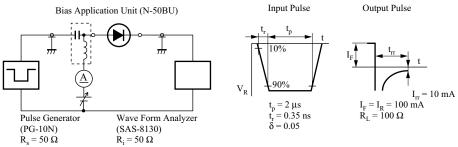
## Unit: mm 1.25±0.10 $0.58^{+0.02}_{-0.03}$ 0.60±0.10 1.90±0.10 2.50±0.10 $0.16^{+0.1}_{-0.06}$ 0.80±0.10 1: Anode 2: Cathode SMini2-F2 Package

Marking Symbol: 3U

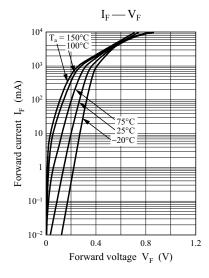
#### ■ Electrical Characteristics $T_a = 25$ °C±3°C

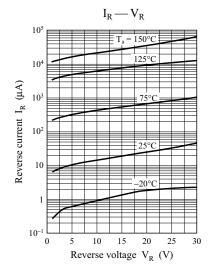
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 0.5 A$		0.34	0.38	V
	V <sub>F2</sub>	$I_F = 0.7 A$		0.36	0.40	
	V <sub>F3</sub>	$I_{\rm F} = 1.0 \text{ A}$		0.38	0.42	
Reverse current	$I_R$	$V_R = 30 \text{ V}$			100	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 10 \text{ V, } f = 1 \text{ MHz}$		40		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA},$ $R_L = 100 \Omega$		13		ns

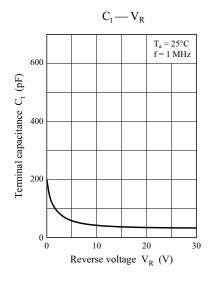
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*: t<sub>rr</sub> measurement circuit

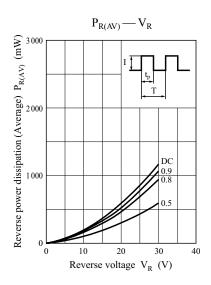


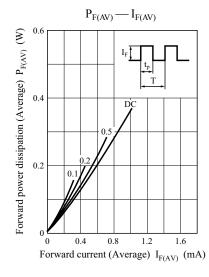
MA21D38 Panasonic

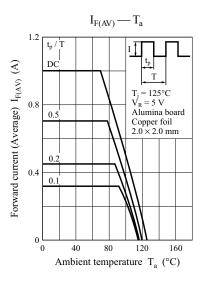


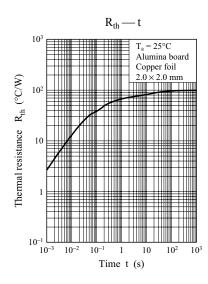












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